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(54) **Title:** METHOD OF REDISTRIBUTION LAYER FORMATION FOR ADVANCED PACKAGING APPLICATIONS

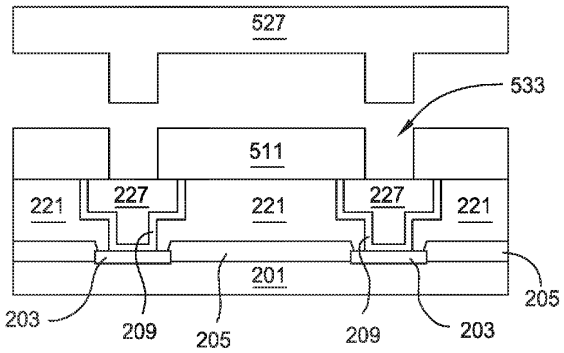


FIG. 5B

(57) **Abstract:** Embodiments of the present disclosure generally describe methods of forming one or more device terminal redistribution layers using imprint lithography. The methods disclosed herein enable the formation of high aspect ratio interconnect structures at lower costs than conventional photolithography and etch processes. Further, the processes and methods described herein desirably remove, reduce, and/or substantially eliminate voids in the surrounding polymer layer formed during the polymer deposition process or subsequent thereto.

WO 2018/236585 A1